

Global and China IC Packaging Research Report to 2020

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Abstracts

This report studies IC Packaging in Global and China market, focuses on price, sales, revenue of each type in global China. This report also focuses on the sales (consumption), production, import and export of IC Packaging in North America, Japan, Europe, India, Southeast Asia and China, forecast to 2020, from 2015.

Split by product types, with sales, revenue, market share and price of each type, as well as the types and each type price of key manufacturers, through interviewing key manufacturers, in 2015 and 2016, covering

BGA

QFN

FC

Bumping

Other

Split by manufacturers, this report focuses on the sales, price of each type, average price of IC Packaging, revenue and market share, for each manufacturer in 2015 and 2016. Top players, covering

ASE

Amkor

SPIL

STATS ChipPac

Powertech Technology

J-devices

UTAC

JECT

ChipMOS

Chipbond

KYEC
STS Semiconductor
Huatian
MPI(Carsem)
Nepes
FATC
Walton
Unisem
NantongFujitsu Microelectronics
Hana Micron
Signetics

Split by regions, this report focuses on the sales (consumption), production, import and export of IC Packaging in North America, Japan, Europe, India, Southeast Asia and China, from 2011 to 2020 (forecast), covering

North America
Europe
Japan
China
India
Southeast Asia

Split by applications, this report focuses on consumption and growth rate of IC Packaging in major applications.

Split by applications, covering

PC
Automotive electronics
Mobile phones and other consumer electronics products
Other

With 136 pages, 168 charts and eight chapters, to display the market present situation and future, clearly and deeply.

Contents

Global and China IC Packaging Research Report to 2020

1 IC PACKAGING OVERVIEW AND EACH TYPE

1.1 Product Overview of IC Packaging

1.1.1 Definition and Product Scope of IC Packaging

1.1.2 Global Market Size (Value and Volume) of IC Packaging 2015-2020

1.13 China Market Size (Value and Volume) of IC Packaging 2015-2020

1.2 Product Segments and Price of Each Type

1.2.1 Product Type of Key Manufacturers

1.2.2 Price List and of Each QFN015 to 2016

1.2.3 Market Share and Growth Rate of Each Type

1.2.4 BGA and Specification

1.2.5 QFN and Specification

1.2.6 FC and Specification

1.3 Price List (Interviewed) of Each Type for Key Manufacturers in 2015 and 2016

1.3.1 Price List (Interviewed) of BGA by Key Manufacturers

1.3.2 Price List (Interviewed) of QFN by Key Manufacturers

1.3.3 Price List (Interviewed) of FC by Key Manufacturers

2 COMPETITION ANALYSIS BY MANUFACTURERS IN GLOBAL AND CHINA

2.1 Global Market IC Packaging Sales and Share List of Key Manufacturers 2015 to 2016

2.2 Global Market IC Packaging Revenue and Share List of Key Manufacturers 2015 to 2016

2.3 Global IC Packaging Average Price List of Key Manufacturers 2015 to 2016

2.4 China Market IC Packaging Sales and Share List of Key Manufacturers 2015 to 2016

2.5 China Market IC Packaging Revenue and Share List of Key Manufacturers 2015 to 2016

2.6 China IC Packaging Average Price List of Key Manufacturers 2015 to 2016

3 SALES AND REVENUE SEGMENTS OF EACH QFN015 TO 2016

3.1 Global Sales and Revenue Segments of Each QFN015 to 2016

3.1.1 Global Sales and Market Share of Each QFN015 to 2016

- 3.1.2 Global Revenue and Market Share of Each QFN015 to 2016
- 3.2 BGA Sales and Growth Rate 2015 to 2020
- 3.3 QFN Sales and Growth Rate 2015 to 2020
- 3.4 FC Sales and Growth Rate 2015 to 2020

4 MARKET SEGMENTS AND FORECAST OF IC PACKAGING BY REGIONS

- 4.1 Sales (Consumption) and Forecast of IC Packaging by Regions 2015-2020
 - 4.1.1 Sales and Forecast of IC Packaging by Regions 2015-2020
 - 4.1.2 Sales Growth Rate Forecast of IC Packaging by Regions 2015 to 2020
- 4.2 Production and Forecast of IC Packaging by Regions 2015 to 2020
 - 4.2.1 Production and Forecast of IC Packaging by Regions 2015 to 2020
 - 4.2.2 Production Growth Rate Forecast of IC Packaging by Regions 2015 to 2020
- 4.3 North America Market Forecast to 2020
 - 4.3.1 North America Sales (Consumption), Production, Import and Export of IC Packaging 2015 to 2020
- 4.4 Europe Market Forecast to 2020
 - 4.4.1 Europe Sales (Consumption), Production, Import and Export of IC Packaging 2015 to 2020
- 4.5 Japan Market Forecast to 2020
 - 4.5.1 Japan Sales (Consumption), Production, Import and Export of IC Packaging 2015 to 2020
- 4.6 India Market Forecast to 2020
 - 4.6.1 India Sales (Consumption), Production, Import and Export of IC Packaging 2015 to 2020
- 4.7 Southeast Asia Market Forecast to 2020
 - 4.7.1 Southeast Asia Sales (Consumption), Production, Import and Export of IC Packaging 2015 to 2020
- 4.8 China Market Forecast to 2020
 - 4.8.1 China Sales (Consumption), Production, Import and Export of IC Packaging 2015 to 2020

5 RAW MATERIALS AND APPLICATIONS

- 5.1 Key Raw Materials and Price Analysis
 - 5.1.1 Key Raw Materials and Suppliers Used for Manufacturing IC Packaging
 - 5.1.2 Price Forecast of Key Raw Materials Used for Manufacturing IC Packaging 2015 to 2020
 - 5.1.3 Cost Structure for Manufacturing IC Packaging

5.2 Applications and Price Scope Interviewed in Major Applications

5.2.1 Price Scope (Interviewed Price to Buyers) of IC Packaging in Major Applications 2015 and 2016

5.2.2 Consumption and Forecast of IC Packaging in Major Applications 2015 to 2020

5.2.2 Consumption Growth Rate Forecast of IC Packaging in Major Applications 2015 to 2020

5.3.3 Consumption Market Share of IC Packaging in Major Applications 2015 to 2020
5.3 PC

5.3.1 PC Analysis

5.3.2 Key Consumers (Buyers) and Contact of IC Packaging in PC

5.4 Automotive electronics

5.4.1 Automotive electronics Analysis

5.4.2 Key Consumers (Buyers) and Contact of IC Packaging in Automotive electronics

5.5 Mobile phones and Other consumer electronics products

5.5.1 Mobile phones and Other consumer electronics products Analysis

5.5.2 Key Consumers (Buyers) and Contact of IC Packaging in Mobile phones and Other consumer electronics products

5.6 Application

5.6.1 Application 4 Analysis

5.6.2 Key Consumers (Buyers) and Contact of IC Packaging in Application

5.7 Application

5.7.1 Application 5 Analysis

5.7.2 Key Consumers (Buyers) and Contact of IC Packaging in Application

6 KEY MANUFACTURERS ANALYSIS OF IC PACKAGING

6.1 ASE

6.1.1 Company Basic Information

6.1.2 IC Packaging Product Segment of ASE by Type

6.1.2.1 BGA and Price in 2015 and 2016

6.1.2.2 QFN and Price in 2015 and 2016

6.1.2.3 FC and Price in 2015 and 2016

6.1.3 IC Packaging Sales, Revenue, Price of ASE 2015 to 2016

6.1.4 Interviewee, Name and Contact

6.2 Amkor

6.2.1 Company Basic Information

6.2.2 IC Packaging Product Segment of Amkor by Type

6.2.2.1 BGA and Price in 2015 and 2016

6.2.2.2 QFN and Price in 2015 and 2016

- 6.2.2.3 FC and Price in 2015 and 2016
- 6.2.3 IC Packaging Sales, Revenue, Price of Amkor 2015 to 2016
- 6.2.4 Interviewee, Name and Contact
- 6.3 SPIL
 - 6.3.1 Company Basic Information
 - 6.3.2 IC Packaging Product Segment of SPIL by Type
 - 6.3.2.1 BGA and Price in 2015 and 2016
 - 6.3.2.2 QFN and Price in 2015 and 2016
 - 6.3.2.3 FC and Price in 2015 and 2016
 - 6.3.3 IC Packaging Sales, Revenue, Price of SPIL 2015 to 2016
 - 6.3.4 Interviewee, Name and Contact
- 6.4 STATS ChipPac
 - 6.4.1 Company Basic Information
 - 6.4.2 IC Packaging Product Segment of STATS ChipPac by Type
 - 6.4.2.1 BGA and Price in 2015 and 2016
 - 6.4.2.2 QFN and Price in 2015 and 2016
 - 6.4.2.3 FC and Price in 2015 and 2016
 - 6.4.3 IC Packaging Sales, Revenue, Price of STATS ChipPac 2015 to 2016
 - 6.4.4 Interviewee, Name and Contact
- 6.5 Powertech Technology
 - 6.5.1 Company Basic Information
 - 6.5.2 IC Packaging Product Segment of Powertech Technology by Type
 - 6.5.2.1 BGA and Price in 2015 and 2016
 - 6.5.2.2 QFN and Price in 2015 and 2016
 - 6.5.2.3 FC and Price in 2015 and 2016
 - 6.5.3 IC Packaging Sales, Revenue, Price of Powertech Technology 2015 to 2016
 - 6.5.4 Interviewee, Name and Contact
- 6.6 J-devices
 - 6.6.1 Company Basic Information
 - 6.6.2 IC Packaging Product Segment of J-devices by Type
 - 6.6.2.1 BGA and Price in 2015 and 2016
 - 6.6.2.2 QFN and Price in 2015 and 2016
 - 6.6.2.3 FC and Price in 2015 and 2016
 - 6.6.3 IC Packaging Sales, Revenue, Price of J-devices 2015 to 2016
 - 6.6.4 Interviewee, Name and Contact
- 6.7 UTAC
 - 6.7.1 Company Basic Information
 - 6.7.2 IC Packaging Product Segment of UTAC by Type
 - 6.7.2.1 BGA and Price in 2015 and 2016

- 6.7.2.2 QFN and Price in 2015 and 2016
- 6.7.2.3 FC and Price in 2015 and 2016
- 6.7.3 IC Packaging Sales, Revenue, Price of UTAC 2015 to 2016
- 6.7.4 Interviewee, Name and Contact
- 6.8 JECT
 - 6.8.1 Company Basic Information
 - 6.8.2 IC Packaging Product Segment of JECT by Type
 - 6.8.2.1 BGA and Price in 2015 and 2016
 - 6.8.2.2 QFN and Price in 2015 and 2016
 - 6.8.2.3 FC and Price in 2015 and 2016
 - 6.8.3 IC Packaging Sales, Revenue, Price of JECT 2015 to 2016
 - 6.8.4 Interviewee, Name and Contact
- 6.9 ChipMOS
 - 6.9.1 Company Basic Information
 - 6.9.2 IC Packaging Product Segment of ChipMOS by Type
 - 6.9.2.1 BGA and Price in 2015 and 2016
 - 6.9.2.2 QFN and Price in 2015 and 2016
 - 6.9.2.3 FC and Price in 2015 and 2016
 - 6.9.3 IC Packaging Sales, Revenue, Price of ChipMOS 2015 to 2016
 - 6.9.4 Interviewee, Name and Contact
- 6.10 Chipbond
 - 6.10.1 Company Basic Information
 - 6.10.2 IC Packaging Product Segment of Chipbond by Type
 - 6.10.2.1 BGA and Price in 2015 and 2016
 - 6.10.2.2 QFN and Price in 2015 and 2016
 - 6.10.2.3 FC and Price in 2015 and 2016
 - 6.10.3 IC Packaging Sales, Revenue, Price of Chipbond 2015 to 2016
 - 6.10.4 Interviewee, Name and Contact
- 6.11 KYEC
 - 6.11.1 Company Basic Information
 - 6.11.2 IC Packaging Product Segment of KYEC by Type
 - 6.11.2.1 BGA and Price in 2015 and 2016
 - 6.11.2.2 QFN and Price in 2015 and 2016
 - 6.11.2.3 FC and Price in 2015 and 2016
 - 6.11.3 IC Packaging Sales, Revenue, Price of KYEC 2015 to 2016
 - 6.11.4 Interviewee, Name and Contact
- 6.12 STS Semiconductor
- 6.13 Huatian
- 6.14 MPI(Carsem)

- 6.15 Nepes
- 6.16 FATC
- 6.17 Walton
- 6.18 Unisem
- 6.19 NantongFujitsu Microelectronics
- 6.20 Hana Micron
- 6.21 Signetics

7 TECHNOLOGY DEVELOPMENT TREND

- 7.1 Manufacturing Process of IC Packaging
- 7.2 Analysis of Manufacturing Process
- 7.3 Development Trend

8 RESEARCH FINDINGS AND CONCLUSION

List Of Tables

LIST OF TABLES AND FIGURES

Figure Picture of IC Packaging

Figure Global Market Size (Value) of IC Packaging 2015-2020

Figure Global Market Size (Volume) of IC Packaging 2015-2020

Figure China Market Size (Value) of IC Packaging 2015-2020

Figure China Market Size (Volume) of IC Packaging 2015-2020

Table Product Type of Key Manufacturers

Table Price List of Each Type

Table Market Share of Each Type

Figure Growth Rate of Each QFN015 to 2016

Figure Picture of BGA

Table Price and Specification of BGA

Figure Picture of QFN

Table Price and Specification of QFN

Figure Picture of FC

Table Price and Specification of FC

Table Price List (Interviewed) of BGA by Key Manufacturers in 2015 and 2016

Table Price List (Interviewed) of QFN by Key Manufacturers in 2015 and 2016

Table Price List (Interviewed) of FC by Key Manufacturers in 2015 and 2016

Table Global Market IC Packaging Sales List of Key Manufacturers 2015 to 2016

Table Global Market IC Packaging Sales Share List of Key Manufacturers 2015 to 2016

Table Global Market IC Packaging Revenue List of Key Manufacturers 2015 to 2016

Table Global Market IC Packaging Revenue Share List of Key Manufacturers 2015 to 2016

Table Global IC Packaging Average Price List of Key Manufacturers 2015 to 2016

Table China Market IC Packaging Sales List of Key Manufacturers 2015 to 2016

Table China Market IC Packaging Sales Share List of Key Manufacturers 2015 to 2016

Table China Market IC Packaging Revenue List of Key Manufacturers 2015 to 2016

Table China Market IC Packaging Revenue Share List of Key Manufacturers 2015 to 2016

Table China IC Packaging Average Price List of Key Manufacturers 2015 to 2016

Table Global Sales of Each QFN015 to 2016

Table Global Sales Market Share of Each QFN015 to 2016

Table Global Revenue of Each QFN015 to 2016

Table Global Revenue Market Share of Each QFN015 to 2016

Figure BGA Sales and Growth Rate 2015 to 2020

Figure QFN Sales and Growth Rate 2015 to 2020

Figure FC Sales and Growth Rate 2015 to 2020

Table Sales and Forecast of IC Packaging by Regions 2015-2020

Figure Sales Growth Rate Forecast of IC Packaging by Regions 2015 to 2020

Table Production and Forecast of IC Packaging by Regions 2015 to 2020

Figure Production Growth Rate Forecast of IC Packaging by Regions 2015 to 2020

Table North America Sales, Production, Import and Export of IC Packaging 2015 to 2020

Table Europe Sales, Production, Import and Export of IC Packaging 2015 to 2020

Table Japan Sales, Production, Import and Export of IC Packaging 2015 to 2020

Table India Sales, Production, Import and Export of IC Packaging 2015 to 2020

Table Southeast Asia Sales, Production, Import and Export of IC Packaging 2015 to 2020

Table China Sales, Production, Import and Export of IC Packaging 2015 to 2020

Table Key Raw Materials and Suppliers List Used for Manufacturing IC Packaging

Table Price Forecast of Key Raw Materials Used for Manufacturing IC Packaging

Table Cost Structure for Manufacturing IC Packaging

Table Price Scope (Interviewed Price to Buyers) of IC Packaging in Major Applications 2015 and 2016

Table Consumption and Forecast of IC Packaging in Major Applications 2015 to 2020

Table Consumption Growth Rate Forecast of IC Packaging in Major Applications 2015 to 2020

Table Consumption Market Share of IC Packaging in Major Applications 2015 to 2020

Table Key Consumers (Buyers) and Contact of IC Packaging in PC

Table Key Consumers (Buyers) and Contact of IC Packaging in Automotive electronics

Table Key Consumers (Buyers) and Contact of IC Packaging in Mobile phones and Other consumer electronics products

Table Key Consumers (Buyers) and Contact of IC Packaging in Application

Table Key Consumers (Buyers) and Contact of IC Packaging in Application

Table ASE Basic Information List

Table IC Packaging Sales, Revenue, Price of ASE 2015 to 2016

Table Amkor Basic Information List

Table IC Packaging Sales, Revenue, Price of Amkor 2015 to 2016

Table SPIL Basic Information List

Table IC Packaging Sales, Revenue, Price of SPIL 2015 to 2016

Table STATS ChipPac Basic Information List

Table IC Packaging Sales, Revenue, Price of STATS ChipPac 2015 to 2016

Table Powertech Technology Basic Information List

Table IC Packaging Sales, Revenue, Price of Powertech Technology 2015 to 2016

Table J-devices Basic Information List
Table IC Packaging Sales, Revenue, Price of J-devices 2015 to 2016
Table UTAC Basic Information List
Table IC Packaging Sales, Revenue, Price of UTAC 2015 to 2016
Table JECT Basic Information List
Table IC Packaging Sales, Revenue, Price of JECT 2015 to 2016
Table ChipMOS Basic Information List
Table IC Packaging Sales, Revenue, Price of ChipMOS 2015 to 2016
Table Chipbond Basic Information List
Table IC Packaging Sales, Revenue, Price of Chipbond 2015 to 2016
Table KYEC Basic Information List
Table IC Packaging Sales, Revenue, Price of KYEC 2015 to 2016

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